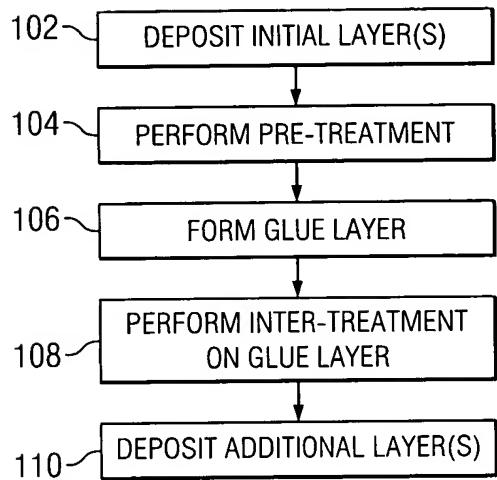


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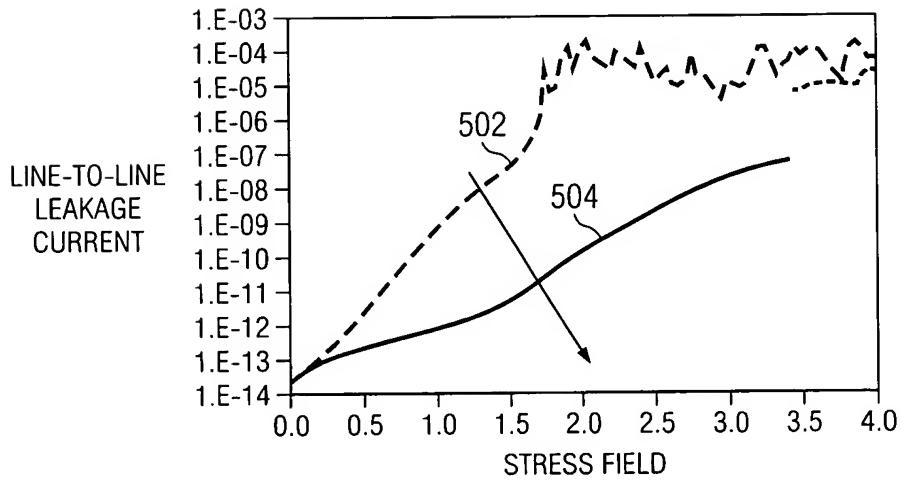
100

Fig. 1



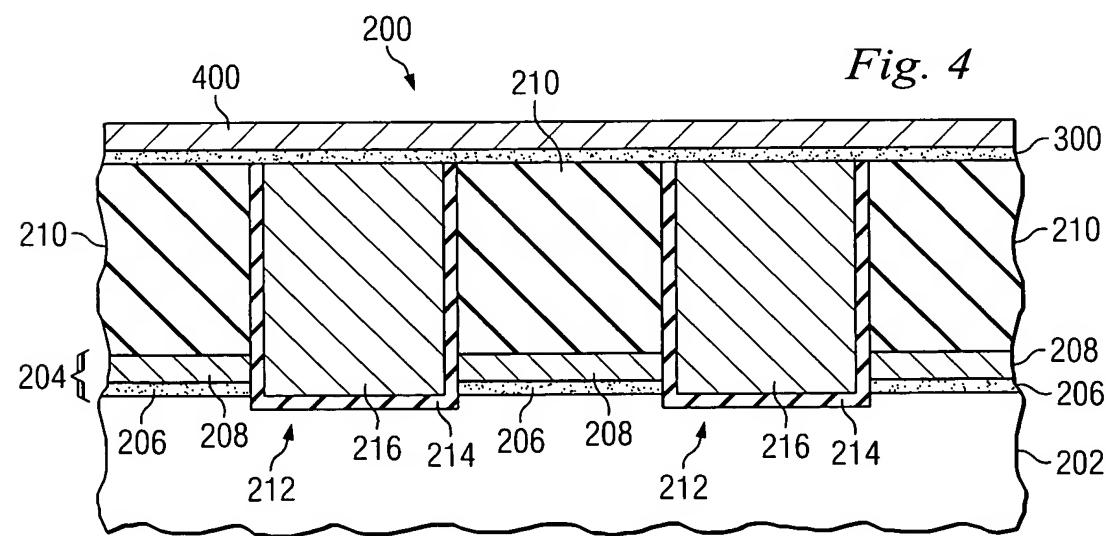
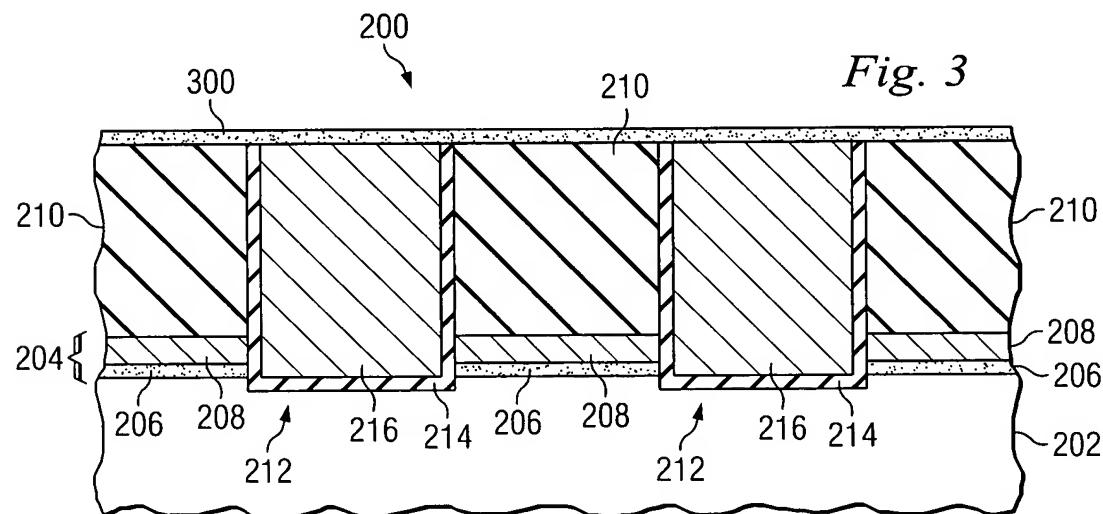
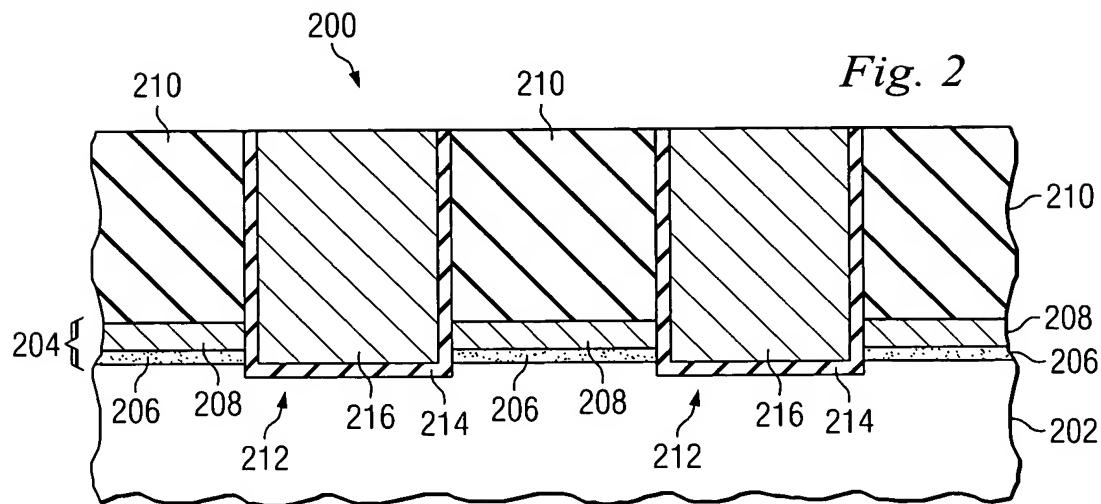
500

Fig. 5



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Fig. 6

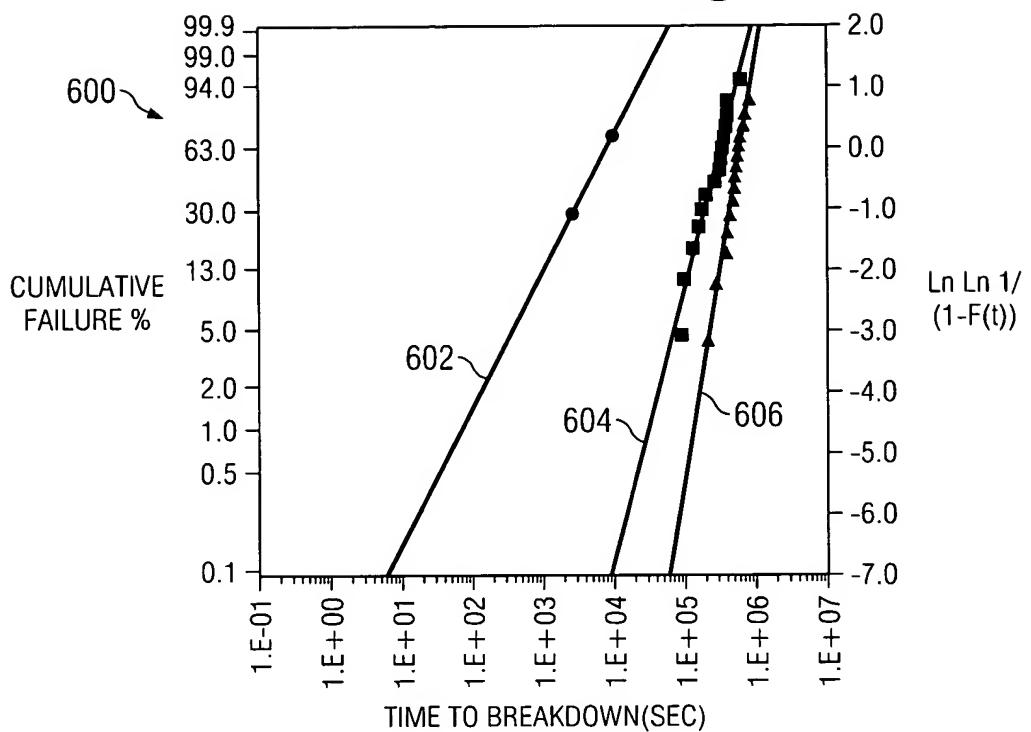


Fig. 7

